

V1.1 Datasheet

N-Channel 30V MOSFET

FEATURES

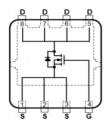
- Advance Trench Process Technology
- High Density Cell Design for Ultra Low On-resistance

PRODUCTY SUMMARY						
V_{DS}	$R_{DS(on)} m(\Omega) Max$					
30	3.5	@V _{GS} =10V				
30	8.0	@V _{GS} =4.5V				

Application

- ●Portable Devices
- ■Consumer Electronics

DFN3333



Mechanical

●Case:DFN3333 Package

Packing Information

Package	Packing
DFN3333	5Kpcs/13"Reel

Maximum Ratings (T _A =25°C unless otherwise specified)							
Parameter	Symbol	Limit	Unit				
Drain-Source Voltage	V _{DS}	30	V				
Gate-Source Voltage	V _{GS}	±20	V				
Continuous Drain Current 1)	I _D	20	А				
Continuous Drain Current 4)	I _{DM}	80	А				
Maximum Power Dissipation	P _D	5	W				
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to 150	°C				

Typical Thermal Resistance						
Parameter Symbol Limit Unit						
Junction-to-Ambient Thermal Resistance 3)	$R_{\theta JA}$	65	°C/W			

Note:

- 1. Pulse width<300us, Duty cycle<2%.
- 2. Fused current that based on wire numbers and diameter.
- 3. Guaranteed by design, not subject to production testing.
- 4. The maximum current rating is package limited.
- 5. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$ =150°C. Ratings are based on low frequency and duty cycles to keepinitial T_J =25°C.

www.mo-semi.com Revision:V1.1



Electrical Characteristics (T _A = 25°C UNLESS OTHERWISE NOTED)						
Characteristics	Comple al	Test Condition	Limits			l lmit
	Symbol	rest Condition	Min	Тур	Max	Unit
Static						
Drain-Source Breakdown Voltage	B _{VDSS}	V_{GS} =0V, I_D =250uA	30			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{D}=250uA$	1.0	1.6	2.0	V
Drain-Source On-State Resistance	R _{DS(on)}	V_{GS} =10V, I_{D} =20A	-	3.0	3.5	mΩ
		V_{GS} =4.5V, I_D =20A	-	5.5	8.0	mΩ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V	-	-	1	uA
GateSource Leakage Current	I _{GSS}	V_{GS} =±20V, V_{DS} =0V	-	-	±100	nA

Dynamic ³⁾						
Total Gate Charge	Qg	V_{DS} =15V, V_{GS} =10V, I_{D} =1.5A	-	53	-	nC
Total Gate Charge	Qg	V _{DS} =15V, V _{GS} =4.5V, I _D =1.5A ^(Note 1,2)	-	26	-	nC
GateSource Charge	Q_{gs}		-	5	-	nC
GateDrain Charge	Q_{gd}		-	12	-	nC
Input Capacitance	C _{iss}		-	2869	-	pF
Output Capacitance	C _{oss}	V _{DS} =15V, V _{GS} =0V, f=200KHz	-	310	-	pF
Reverse Transfer Capacitance	C _{rss}	. 2001412	-	271	-	pF

Switching						
TurnOn Delay Time	t _{d(on)}	\/ 4F\/		17	-	ns
TurnOn Rise Time	t _r	V _{DS} =15V, Rload=10Ohm, Vgen=10V, Rg=3Ohm		12	-	ns
TurnOff Delay Time	t _{d(off)}			58	-	ns
TurnOff Fall Time	t _f	Kg=30IIII		11	-	ns

DrainSource Diode						
Maximum Continuous Body Diode Forward Current	Is	-	-	-	1.2	А
Diode Forward Voltage	V _{SD}	I _S =1.0A, V _{GS} =0V	-	-	1.5	V

Note:

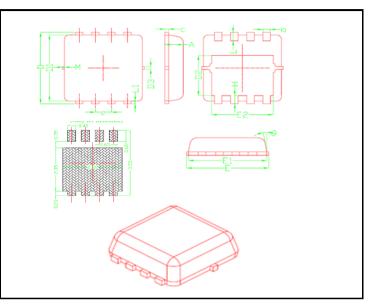
- 1. Pulse width<300us, Duty cycle<2%.
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$ =150°C. Ratings are based on low frequency and duty cycles to keep initial T_J =25°C.
- 4. The maximum current rating is package limited.
- $5.\ R_{QJA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch2 with 2oz.square pad of copper.
- 6. Guaranteed by design, not subject to production testing.

www.mo-semi.com Revision:V1.1

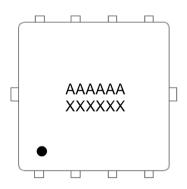


Package Outline Dimensions (inches and millimeters)

DFN3333							
	Dimensions						
SYMBOL	Millin	neters	Inches				
	Min	Max	Min	Max			
Α	0.70	0.80	0.028	0.031			
b	0.25	0.35	0.010	0.014			
С	0.10	0.25	0.004	0.010			
D	3.25	3.45	0.128	0.136			
D1	3.00	3.20	0.118	0.126			
D2	1.78	1.98	0.070	0.078			
D3	ı	0.13	-	0.005			
E	3.20	3.40	0.126	0.134			
E1	3.00	3.20	0.118	0.126			
E2	2.39	2.59	0.094	0.102			
е		0.65	BSC	•			
Н	0.30	0.50	0.012	0.020			
L	0.30	0.50	0.012	0.020			
L1	0.1	13	-	0.005			
θ	-	12 °	-	12 °			
M	-	0.15	-	0.006			



Marking Information



AAAAAA = Product number

XXXXXX = Tracking number

Third line = Pin1 Point

Motive reserves the right to make changes without further notice to any products herein. Motive makes no warranty · representation or guarantee regarding the suitability of its products for any particular purpose, nor does Motive assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in Motive data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Motive does not convey any license under its patent rights nor the rights of others. Motive products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Motive product could create a situation where personal injury or death may occur. Should Buyer purchase or use Motive products for any such unintended or unauthorized application, Buyer shall indemnify and hold Motive and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims · costs · damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Motive was negligent regarding the design or manufacture of the part.

www.mo-semi.com Revision:V1.1